		7 m	DB	Time stamp
L Number	Hits	Search Text	USPAT;	2003/10/23 10:34
41	241	(wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		(attach\$5 or bond\$4) and ((balls ad) gird	EPO; JPO;	
		adj arrays) or (BGA)) and semiconductor	DERWENT;	
ļ		and (dic\$4 or cut\$4 or separat\$5)) and	IBM TDB	
	ļ	@ad<=20000616	USPAT;	2003/10/23 10:35
42	241	(wafer and (metal adj (film or layer)) and		2003/10/23 10:00
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
1	ľ	adj arrays) or ("BGA")) and semiconductor	EPO; JPO;	
i	ļ.	and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
ļ		@ad<=20000616	IBM_TDB	
43	1	((wafer same (metal adj (film or layer))	USPAT;	2003/10/23 10:36
43	- 1	same (attach\$5 or bond\$4) same ((balls adj	US-PGPUB;	
		grid adj arrays) or ("BGA")) same	EPO; JPO;	
		semiconductor same (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5))) and @ad<=20000616	IBM TDB	
	240	(438/15).CCLS.	USPAT	2003/05/20 07:57
-			USPAT	2002/07/03 08:58
- 1		(438/113).CCLS.	USPAT	2002/07/03 08:58
-	94	(438/110).CCLS.	USPAT	2002/07/03 08:58
-	59	(438/114).CCLS.	USPAT	2002/07/03 00:30
_	681	438/15,110,113,114.ccls.		2002/12/19 14:30
_	401	438/15.110.113.114.ccls. and test\$3	USPAT	
_	272	(438/15,110,113,114.ccls. and test\$3) and	USPAT	2001/08/07 15:10
		(dice\$4 or cut\$5)		1
	901	438/15,110,113,114.ccls.	USPAT;	2002/02/04 09:53
_	JU1	100/ 10/ 10/ 10/ 10/ 10/ 10/ 10/ 10/ 10/	EPO; JPO;	
ļ			DERWENT	i
		438/15,110,113,114.ccls. and test\$3	USPAT;	2002/02/04 09:54
-	460	430/13,110,113,114,0013. and testys	EPO; JPO;	
			DERWENT	
			USPAT;	2002/02/05 08:26
-	325	(438/15,110,113,114.ccls. and test\$3) and		=====================================
ļ		(dic\$5 or cut\$5)	EPO; JPO;	
1			DERWENT	2003/05/21 08:46
_	5	(("6077757") or ("6335224") or ("6309943")	USPAT	2003/03/21 00.40
ļ		or ("6309909") or ("6326697")).PN.		2002/02/05 09:49
<u>-</u>	7	(("6077757") or ("6335224") or ("6309943")	USPAT	2002/02/05 09:49
	,	or ("6309909") or ("6326697") or		1
		("5858815") or ("5137836")).PN.		
	326	(438/15,110,113,114.ccls. and test\$3) and	USPAT;	2002/02/05 08:28
-	320	(dic\$5 or cut\$5)	EPO; JPO;	
		(UICTS OF CREAS)	DERWENT	
1	_	((438/15,110,113,114.ccls. and test\$3) and	USPAT;	2002/02/05 08:33
	0	((438/13,110,113,114.0013. and testing) and	EPO; JPO;	
		(dic\$5 or cut\$5)) and (magnet\$7 adj	DERWENT	
1		align\$5)		2002/02/05 08:32
-	170	((438/15,110,113,114.ccls. and test\$3) and	EPO; JPO;	=====================================
Į į		(dic\$5 or cut\$5)) and (align\$5)	EPO; JPO;	
			DERWENT	2002/02/05 08:56
	2705	magnet\$7 adj align\$5	USPAT;	2002/02/03 08:36
			EPO; JPO;	
			DERWENT	
	0	(magnet\$7 adj align\$5) and (wafer adj20	USPAT;	2002/02/05 08:37
_		dielectric adj tape)	EPO; JPO;	
1		diefectio adj cape/	DERWENT	
	_	- s	USPAT;	2002/02/05 08:37
-	0	wafer adj20 dielectric adj tape	EPO; JPO;	
		1	DERWENT	
			1	2002/02/05 08:38
	0	wafer adj dielectric adj tape	USPAT;	2002/02/03 00.30
1		1	EPO; JPO;	
			DERWENT	1 0000 /00 /05 00 53
1_	248	(magnet\$7 adj align\$5) and semiconductor	USPAT;	2002/02/05 08:57
-	230	,y	EPO; JPO;	
1			DERWENT	1
	٥ ا	((magnet\$7 adj align\$5) and ring) and	USPAT;	2002/02/05 08:49
-	1	((magnets, adj alignos, and ling, and (charged adj slot)	EPO; JPO;	
	i	(Charged ad) Sioci	DERWENT	
		,	USPAT;	2002/02/05 08:49
-	0		EPO; JPO;	
		slot)	DERWENT	
				2002/02/05 08:50
-	613	(magnet\$7 adj align\$5) and ring	USPAT;	2002/02/03 00:30
I			EPO; JPO; DERWENT	

_	47	((magnet\$7 adj align\$5) and ring) and	USPAT;	2002/02/05 08:51
	• •	semiconductor	EPO; JPO;	1
ĺ	İ		DERWENT	0000 (00 (05 00 . 50
-	3066	optically adj align\$5	USPAT;	2002/02/05 08:56
		-	EPO; JPO;	
			DERWENT	0000/00/05 00:57
_	612	(optically adj align\$5) and semiconductor	USPAT;	2002/02/05 08:57
			EPO; JPO;	
			DERWENT	2003/06/02 08:10
-	8	(("6077757") or ("6335224") or ("6309943")	USPAT	2003/06/02 08:10
		or ("6309909") or ("6326697") or		
· '		("5858815") or ("5137836") or		
1		("4781969")).PN.	USPAT;	2002/07/03 08:13
-	10260	wood.inv.	US-PGPUB;	2002,01,00
			EPO; JPO;	
		,	DERWENT;	
			IBM TDB	
		1	USPAT;	2002/07/03 08:13
-	539	wood.inv. and alan	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	222	(wood.inv. and alan) and (micron adj	USPAT;	2002/07/03 08:14
-	232	technology)	US-PGPUB;	
		technology)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
1	1	("6268650").PN.	USPAT	2002/12/20 10:24
-	425		USPAT	2002/07/08 08:43
_	331	I 1	USPAT	2002/07/08 08:57
ļ -	140	1 ''	USPAT	2002/07/08.08:57
<u>-</u>	90	7	USPAT	2002/07/08 08:57
	425		USPAT	2002/07/08 08:43
	331	1 '	USPAT	2002/07/08 08:57
l - .	140		USPAT	2002/07/08 08:57
_	90	(438/114).CCLS.	USPAT	2002/07/08 14:32
_	13	(("6389689") or ("5977629") or ("5796170")	USPAT	2002/07/08 10:35
	İ	or ("6326700") or ("6268650") or		1
		("5858815") or ("5817535") or ("5770032")		
		or ("4781969") or ("5073840") or		
	1	("5696033") or ("5834839") or		
1		("6160714")).PN.	USPAT	2002/07/09 09:56
-	8	(("6309909") or ("5858815") or ("5137836")	USFAI	2002/07/03 03:30
		or ("6077757") or ("6326697") or		
		("6165885") or ("5834320") or		
		("4781969")).PN. (wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 15:00
-	0	(dielectric adj (layer or film))) same	US-PGPUB;	
		test\$3 same (cut\$4 or dic\$3 or separat\$3)	EPO; JPO;	
		reachs same leachs or group or pobarachs.	DERWENT;	
			IBM TDB	
l _	0	(wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 14:07
-	1	(dielectric adj (layer or film))) same	US-PGPUB;	
		test\$3 same (cut\$4 or dic\$3 or separat\$3)	EPO; JPO;	
		200040 00000 (000)11 000	DERWENT;	
]			IBM_TDB	
i _	1 9	wafer adj (bond\$3 or attach\$3) near4	USPĀT;	2002/12/19 14:07
_	1	(dielectric adj (layer or film))	US-PGPUB;	1
1		,	EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
_	1 0	(wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 14:38
		(dielectric adj (layer or film))) same	US-PGPUB;	
	1	test\$3	EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	2002/12/10 14:20
-	963	438/15,110,113,114.ccls.	USPAT	2002/12/19 14:38

-	1212	438/15,110,113,114.ccls.	USPAT; US-PGPUB;	2002/12/19 14:38
			EPO; JPO; DERWENT;	
			IBM_TDB USPAT;	2002/12/19 14:40
-	0	438/15,110,113,114.ccls. and ((wafer adj (bond\$3 or attach\$3) near4 (dielectric adj	US-PGPUB;	2002/12/19 14.40
		(layer or film))) same test\$3)	EPO; JPO; DERWENT;	
		(wafer adj (dielectric adj (layer or	IBM_TDB USPAT;	2002/12/20 08:18
-	9	film))) same test\$3	US-PGPUB; EPO; JPO;	
			DERWENT;	
_	13	(("5834839") or ("6389689") or ("6160714")	IBM_TDB USPAT	2002/12/19 15:19
_		or ("5977629") or ("6326700") or ("6268650") or ("5858815") or ("5817535")		
		or ("5770032") or ("5796170") or	Ì	
		("4781969") or ("5073840") or ("5696033")).PN.		0000/10/00 00:40
-	85	<pre>wafer same dielectric same test\$3 same (cut\$3 or dic\$3 or slic\$3)</pre>	USPAT; US-PGPUB;	2002/12/20 08:42
		(60043 61 61040 61 61114)	EPO; JPO; DERWENT;	
			IBM_TDB USPAT;	2002/12/20 09:38
-	78	<pre>(wafer same dielectric same test\$3 same (cut\$3 or dic\$3 or slic\$3)) and</pre>	US-PGPUB;	2002/12/20 03:30
		semiconductor	EPO; JPO; DERWENT;	
	240	(wafer same (dielectric adj (layer or	IBM_TDB USPAT;	2002/12/20 09:35
-	348	film))) same test\$3	US-PGPUB; EPO; JPO;	
			DERWENT;	
_	322	((wafer same (dielectric adj (layer or	IBM_TDB USPAT;	2002/12/20 09:38
		film))) same test\$3) and semiconductor	US-PGPUB; EPO; JPO;	
			DERWENT; IBM TDB	
_	98	(((wafer same (dielectric adj (layer or	USPĀT; US-PGPUB;	2002/12/20 09:39
		<pre>film))) same test\$3) and semiconductor) and (cut\$3 or dic\$3)</pre>	EPO; JPO;	
			DERWENT; IBM_TDB	
-	1 3	("6424023").PN. (("5897337") or ("5858815") or	USPAT USPAT	2002/12/20 10:24 2002/12/23 11:53
-		("6389689")).PN.	USPAT	2002/12/23 11:53
-	9187	((balls adj grid adj arrays) or (BGA)) and	USPAT; US-PGPUB;	2003/05/20 07:59
		semiconductor	EPO; JPO;	
			DERWENT; IBM_TDB	
-	4418	(((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic\$4 or cut\$4 or	USPĀT; US-PGPUB;	2003/05/20 08:02
		separat\$5)	EPO; JPO; DERWENT;	
			IBM_TDB	2003/05/20 08:04
-	4476	(((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic\$4 or cut\$4 or	USPAT; US-PGPUB;	2003/03/20 00:04
		separat\$5 or saw\$4)	EPO; JPO; DERWENT;	
	055	((((balls adj grid adj arrays) or (BGA))	IBM_TDB USPAT;	2003/05/20 08:04
-	955	and semiconductor) and (dic\$4 or cut\$4 or	US-PGPUB; EPO; JPO;	
		<pre>separat\$5)) and (metal adj (film or layer))</pre>	DERWENT;	
İ	1		IBM TDB	<u> </u>

				10000705700 00-04
-	970	((((balls adj grid adj arrays) or (BGA))	USPAT; US-PGPUB;	2003/05/20 08:04
		and semiconductor) and (dic\$4 or cut\$4 or separat\$5 or saw\$4)) and (metal adj (film	EPO; JPO;	
		or layer))	DERWENT;	
		Of Tayer,	IBM TDB	
	1	("20010052642").PN.	US-PGPUB	2003/05/20 08:12
	472	wafer and (metal adj (film or layer)) and	USPAT;	2003/05/20 08:52
i	*	(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	i
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)	DERWENT; IBM TDB	
		11 (S'1) and	USPAT;	2003/10/23 10:34
-	233	(wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	2003, 20, 20
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	i i
		@ad<=20000616	IBM_TDB	
· _	212	((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 08:23
		and (attach\$5 or bond\$4) and ((balls ad)	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	1
		semiconductor and (dic\$4 or cut\$4 or	DERWENT; IBM TDB	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TOB	
	206	or cut\$6 or saw\$5) ((wafer and (metal adj (film or layer))	USPAT;	2003/05/20 09:06
-	206	and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
•		grid adi arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
]		or cut\$6)	USPAT;	2003/05/20 10:06
-	1	(((wafer adj semiconductor) same (metal adj (film or layer)) same (attach\$5 or	US-PGPUB;	2000, 00, 20
1		bond\$4) same ((balls adj grid adj arrays)	EPO; JPO;	
		or (BGA)) same (dic\$4 or cut\$4 or	DERWENT;	1
		separat\$5)) same (dic\$5 or cut\$6 or	IBM_TDB	
		saw\$5)) and @ad<=20000616		0003/05/01 00:00
	212	((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 09:00
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB; EPO; JPO;	
	ļ	grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB	
		or cut\$6 or saw\$5)	_	
_	172	(((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 09:24
	1	and (attach\$5 or bond\$4) and ((balls ad)	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	1
		semiconductor and (dic\$4 or cut\$4 or	DERWENT; IBM_TDB	
		separat\$5)) and @ad<=20000616) and (dic\$5 or cut\$6 or saw\$5)) and dic\$5	1511_155	
	92	(((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 09:35
-	92	and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adi arrays) or (BGA)) and	EPO; JPO;	
1		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
1		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
	1	or cuts6 or saw\$5)) and (dicing or diced)	USPAT;	2003/05/21 09:36
-	70	((((wafer and (metal adj (film or layer))	US-PGPUB;	2003,03,21 03.30
		and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and	EPO; JPO;	
	1	semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
		or cut\$6 or saw\$5)) and (dicing or	_	
		diced)) and (individual\$3 or each)	110.000	2003/05/21 09:36
-	70	((((wafer and (metal adj (film or layer))	USPAT; US-PGPUB;	2003/03/21 09:30
		and (attach\$5 or bond\$4) and ((balls adj	EPO; JPO;	
		grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		semiconductor and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
		or cut\$6 or saw\$5)) and (dicing or	'	
		diced)) and (individual\$3)	<u> </u>	
		1		

		1 / 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 - 1 -	USPAT;	2003/05/21 09:37
-	6	((((wafer and (metal adj (film or layer))	+	2003/ 00/ 22 00:07
	ļ	and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	1
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	ļ
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB	
	i	or cut\$6 or saw\$5)) and (dicing or	-	
		or cutso of sawso, and (dieting of		
		diced)) and (individual\$3 adj device)	**************************************	2003/06/02 09:37
l _	1 2	(("6344401") or ("6566745")).PN.	USPAT	2003/00/02 03:37